Middle Power LED Series
3030

LM301H ONE

For Horticulture Lighting



Features & Benefits

- Middle power LED
- Mold resin for high reliability
- Standard form factor for design flexibility (3.0 × 3.0 mm)

SAMSUNG

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1. Characteristics

a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	T_a	-40 ~ +85	℃	-
Storage Temperature	T_{stg}	-40 ~ +120	℃	-
LED Junction Temperature	T_j	110	℃	-
Forward Current	I_F	200	mA	-
Pulse Forward Current	I_{FP}	300	mA	Duty 1/10, pulse width 10ms
Assembly Process Temperature	-	260 <10	℃ s	-
ESD (HBM)	-	5	kV	-

b) Electro-optical Characteristics (I_F = 65 mA, Ts = 25℃)

Item	Unit	Rank	Bin	Min.	Typ.	Max.
Forward Voltage (V_F)	V	XA	AY	2.6	-	2.7
			AZ	2.7	-	2.8
			A1	2.8	-	2.9
Reverse Voltage (@ 5 mA)	V			0.7	-	1.2
Color Rendering Index (R_a)	-			-	-	-
Thermal Resistance (junction to solder point)	℃/W			-	7.5	-
Beam Angle	°			-	120	-

Note:

Samsung maintains measurement tolerance of: forward voltage = ±0.1 V, luminous flux = ±5 %, CRI = ±3

c) Electro-optical Characteristics (I_F = 65 mA, T_s= 25℃)

Item	Nominal CCT	SU		SV	
		Min.	Max.	Min.	Max.
		35	38	38	43
Luminous Flux (Φ_v)	ONE				

Note:

Samsung maintains measurement tolerance of: forward voltage = ±0.1V, luminous flux = ±5 %, CRI = ±3

2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	P	M	W	H	D	3	2	A	M	H	1	X	A	H	0	S	0

Digit	PKG Information	Code	Specification
1 2 3	Samsung Package Middle Power	SPM	
4 5	Color	WH	White
6	Product Version	D	Dispensing
7 8 9	Form Factor	32A	3.0 x 3.0 x 0.7 mm; 2 pads;
10	Sorting Current (mA)	M	65 mA
11	Chromaticity Coordinates	H	Horticulture
12	CRI	1	Free
13 14	Forward Voltage (V)	XA	2.6~2.9 Bin Code: AY 2.6~2.7 / AZ 2.7~2.8 / A1 2.8~2.9
15 16	Color bin	H0	Bin Code HE, HF, HG, HH, HJ, HK, HL, HM
17 18	Luminous Flux	S0	SU, SV
		SU	Bin Code: SU 35.0 ~ 38.0
		SV	SV 38.0 ~ 43.0

a) Luminous Flux Bins(I_F = 65 mA, T_s= 25℃)

Nominal CCT	Product Code	Flux Bin	Flux Range (Φ_v, lm)
ONE	SPMWHD32AMH1XAH0S0	SU	35.0 ~ 38.0
		SV	38.0 ~ 43.0

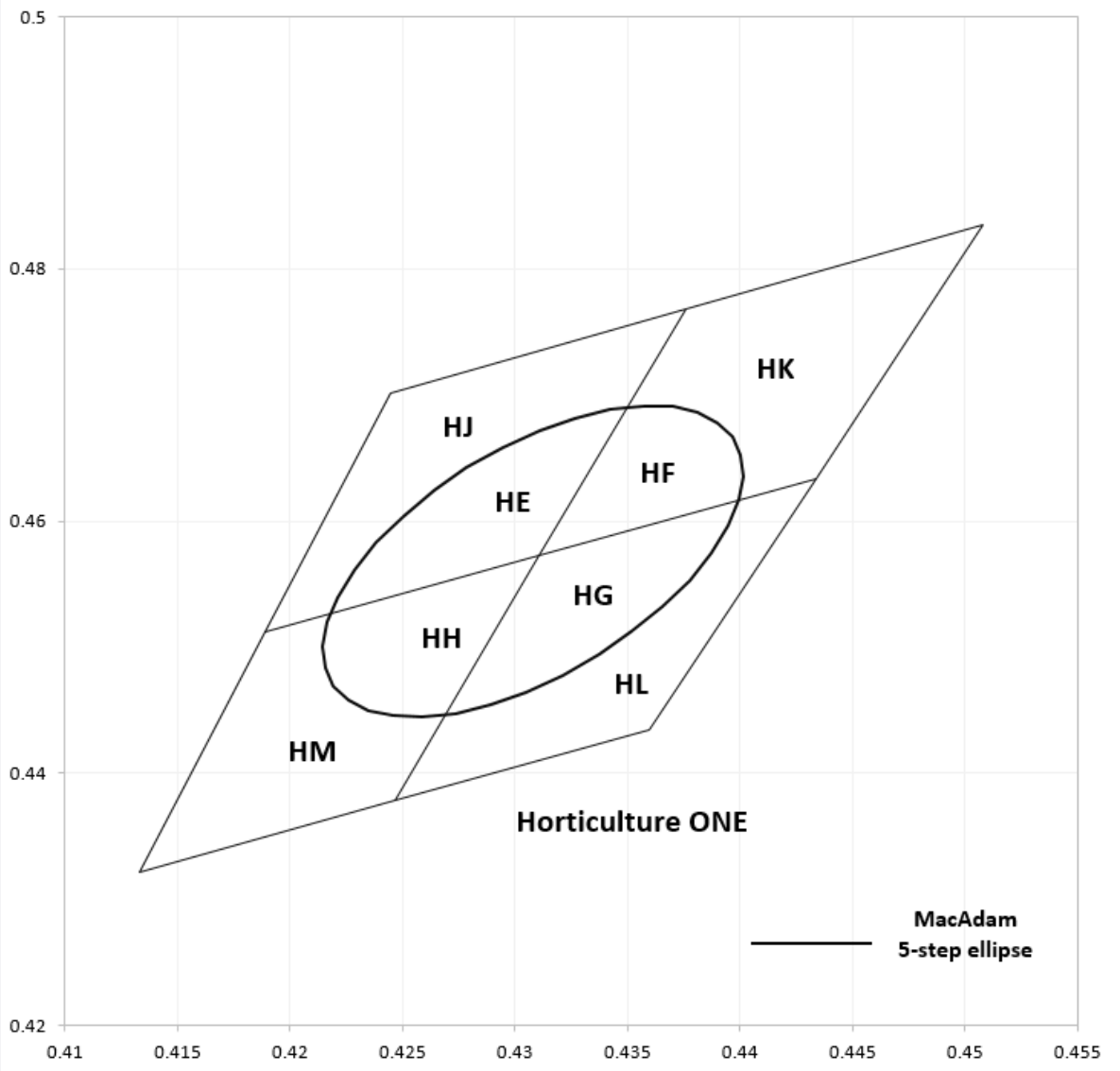
b) Color Bins (I_F = 65 mA, Ts= 25℃)

Nominal CCT (K)	Product Code	Color Rank		Chromaticity Bins
ONE	SPMWHD32AMH1XAH0S0	H0	Whole bin	HE, HF, HG, HH, HJ, HK, HL, HM

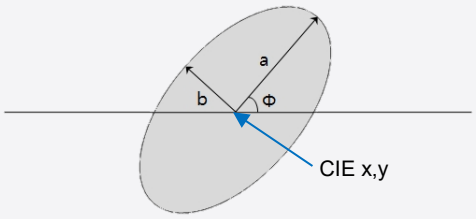
c) Voltage Bins (I_F = 65 mA, T_s = 25℃)

CRI (R_a) Min.	Nominal CCT (K)	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
-	-	-	XA	AY	2.6 ~ 2.7
				AZ	2.7 ~ 2.8
				A1	2.8 ~ 2.9

d) Chromaticity Region & Coordinates (I_F = 65 mA, T_s = 25℃)



e) Chromaticity Region & Coordinates (I_F = 65 mA, T_s = 25℃)



Region	CIE x	CIE y	Region	CIE x	CIE y
HJ	0.4245	0.4702	HK	0.4376	0.4768
	0.4376	0.4768		0.4508	0.4835
	0.4311	0.4573		0.4434	0.4634
	0.4189	0.4512		0.4311	0.4573
HL	0.4311	0.4573	HM	0.4189	0.4512
	0.4434	0.4634		0.4311	0.4573
	0.436	0.4434		0.4247	0.4378
	0.4247	0.4378		0.4133	0.4322

MacAdam Ellipse (H3, H5)					
Step	CIE x	CIE y	θ	a	b
5-step	0.4308	0.4568	58.22	0.0139	0.0068

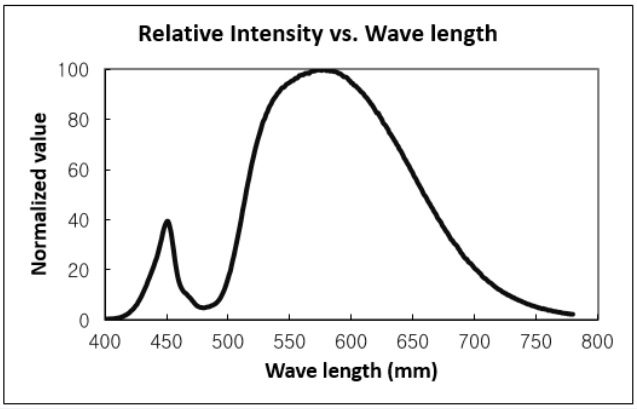
Note:

Samsung maintains measurement tolerance of: Cx, Cy = ±0.005

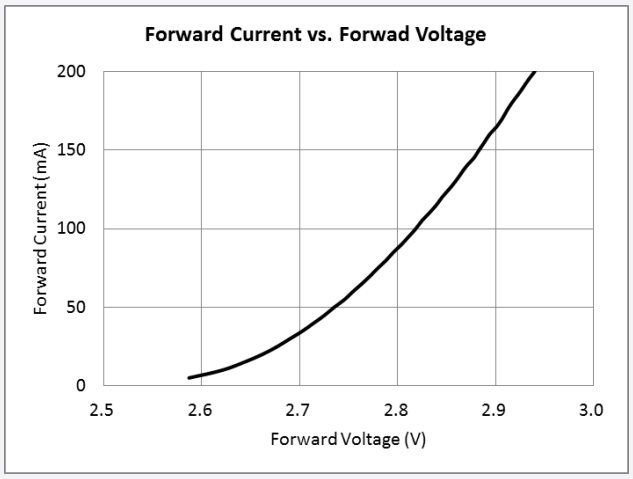
3. Typical Characteristics Graphs

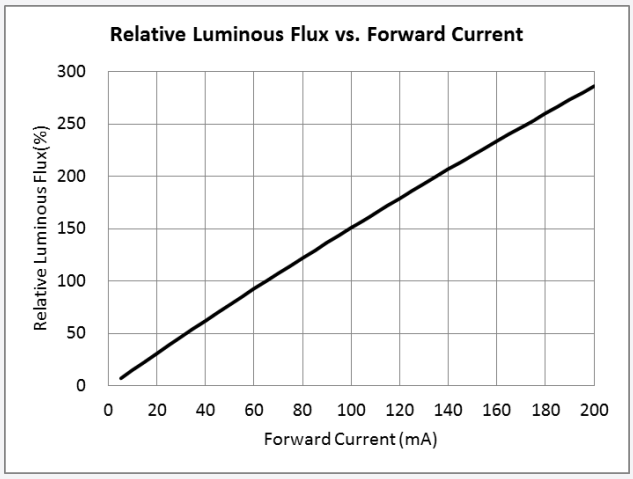
a) Spectrum Distribution (I_F = 65 mA, T_s = 25℃)

CCT : Horticulture ONE

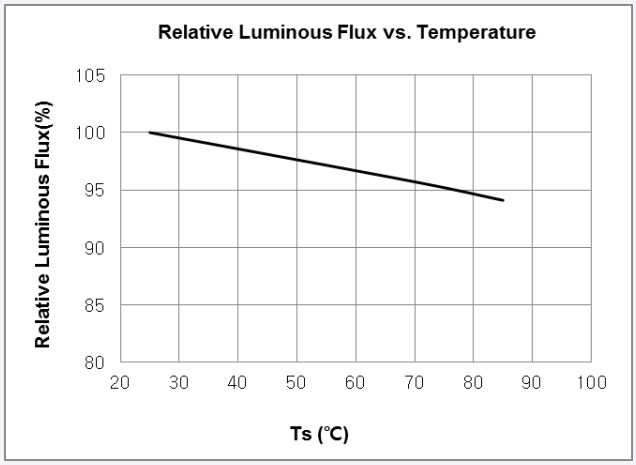


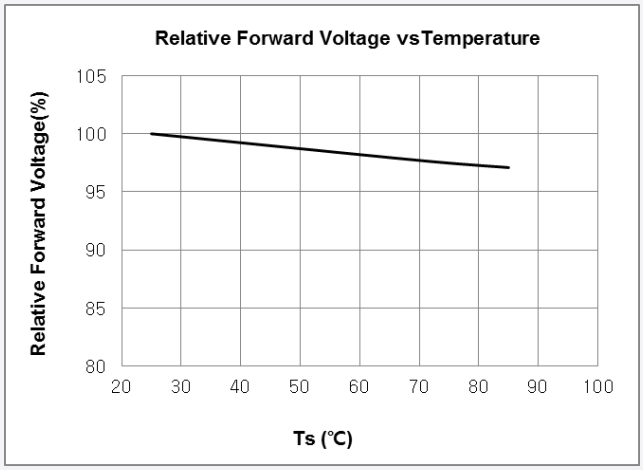
b) Forward Current Characteristics (Ts = 25℃)



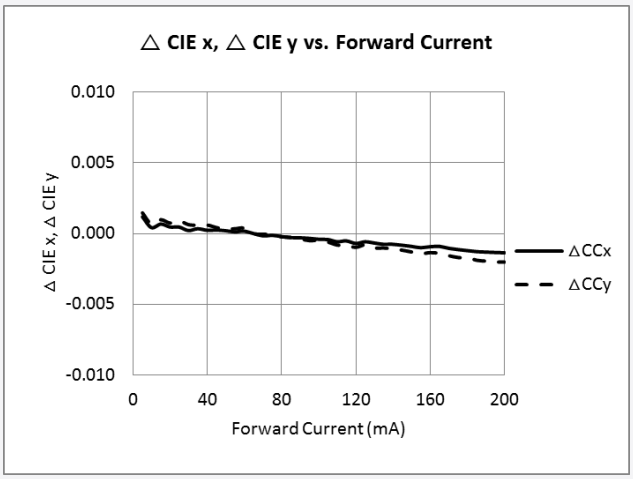


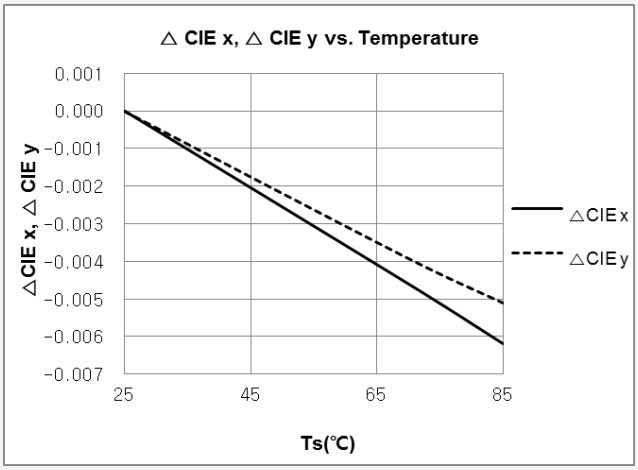
c) Temperature Characteristics (IF = 65 mA)



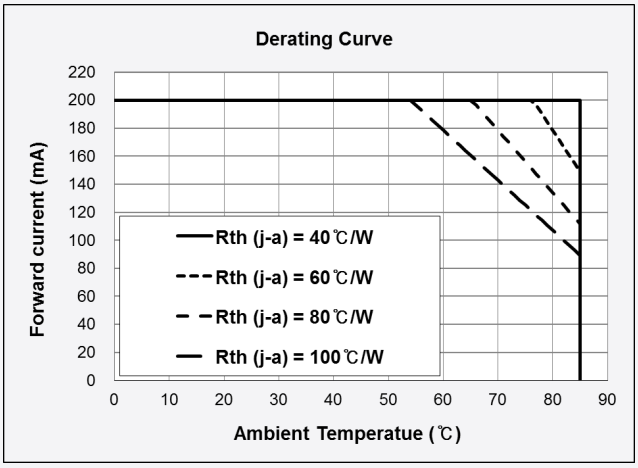


d) Color Shift Characteristics, T_s = 25℃, I_F = 65 mA

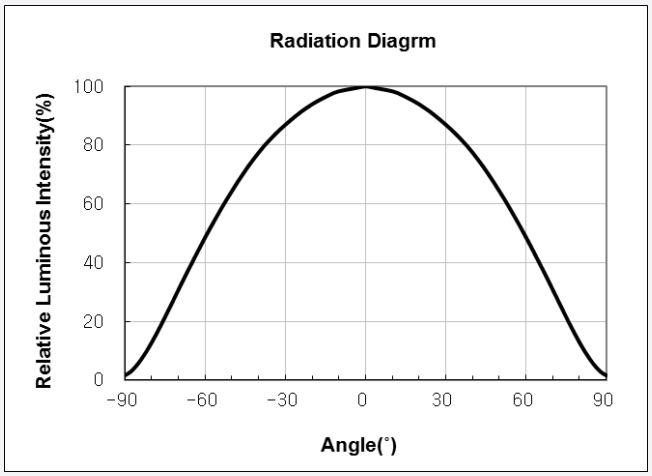




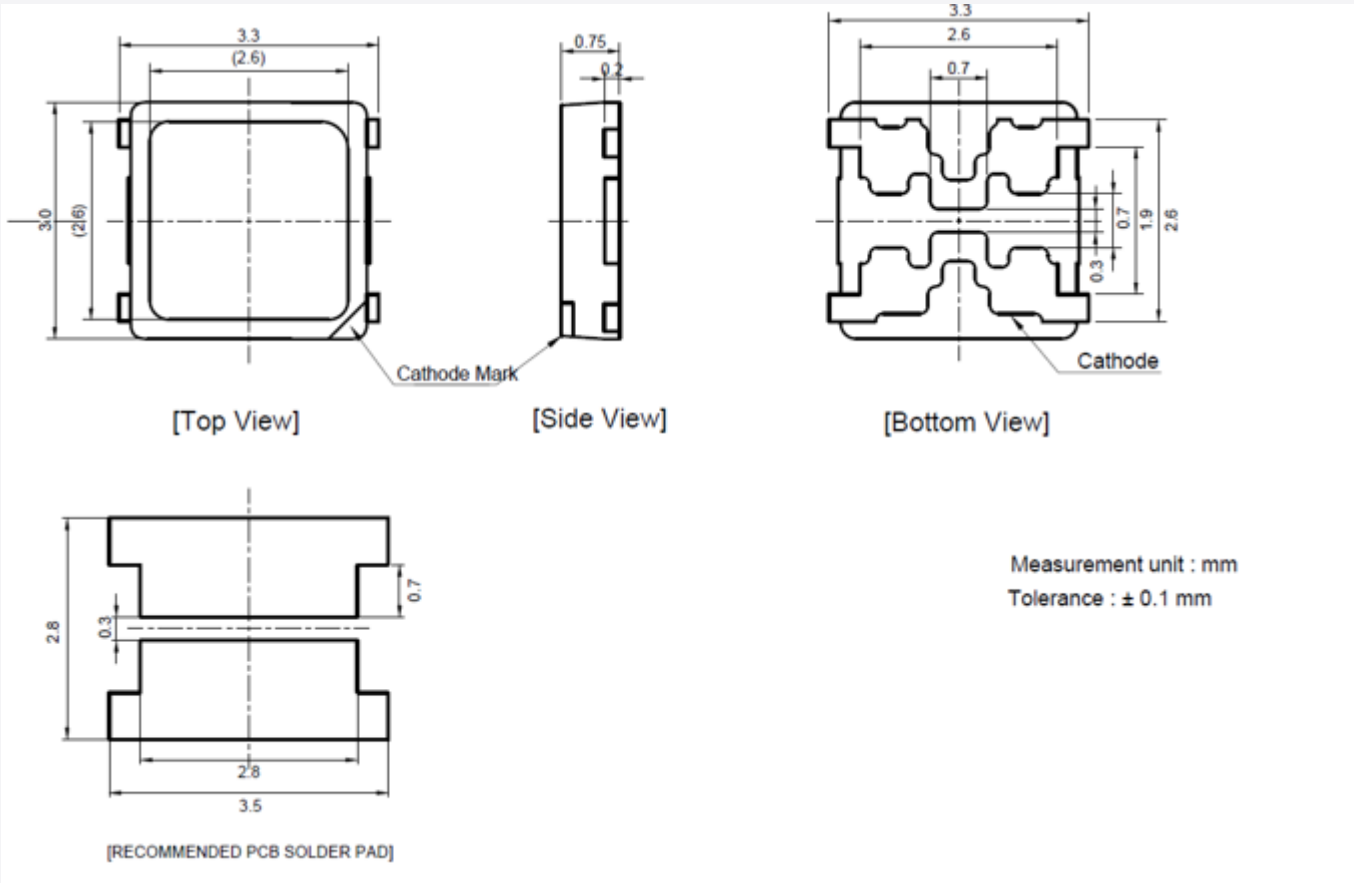
e) Derating Curve



f) Beam Angle Characteristics (T_s = 25℃, I_F = 65 mA)



4. Outline Drawing & Dimension



Notes:

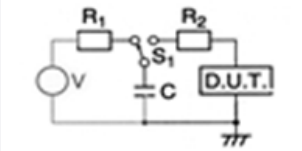
1) This LED has built-in ESD protection device(s) connected in parallel to LED chip(s).
2) T_s point and measurement method:
   ① Measure one point at the cathode pad, if necessary remove PSR of PCB to reach T_s point.
   ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

Precautions:

1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED`s characteristics should be carefully checked before and after such repair.
3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

5. Reliability Test Items & Conditions

a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample No.
High Temperature Life Test	85℃, DC 200 mA	1000 h	22
High Temperature Humidity Life Test	60℃, 90 % RH, DC 200 mA	1000 h	22
Low Temperature Life Test	-40℃, DC 200 mA	1000 h	22
Thermal Cycle	-45℃ / 15 min ↔ 125℃ / 15 min → Hot plate 180℃	500 cycles	100
High Temperature Storage	120℃	1000 h	11
Low Temperature Storage	-40℃	1000 h	11
ESD (HBM)	 R_1: 10 MΩ R_2: 1.5 kΩ C: 100 pF V: ±5 kV	5 times	30

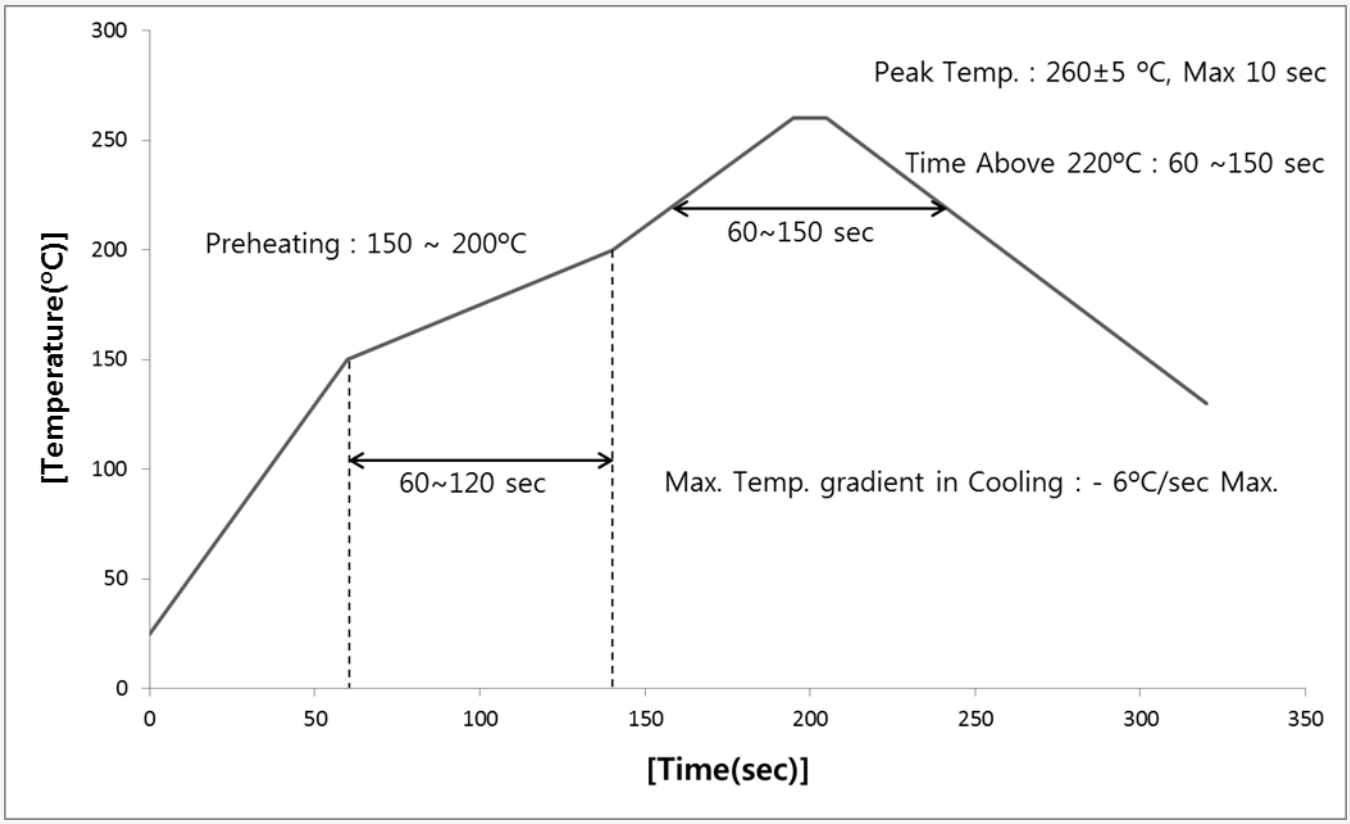
b) Criteria for Judging the Damage

Item	Symbol	Test Condition (Ts = 25℃)	Limit	
			Min	Max
Forward Voltage	V_F	I_F = 65 mA	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	Φ_v	I_F = 65 mA	Init. Value * 0.7	Init. Value * 1.1

6. Soldering Conditions

a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



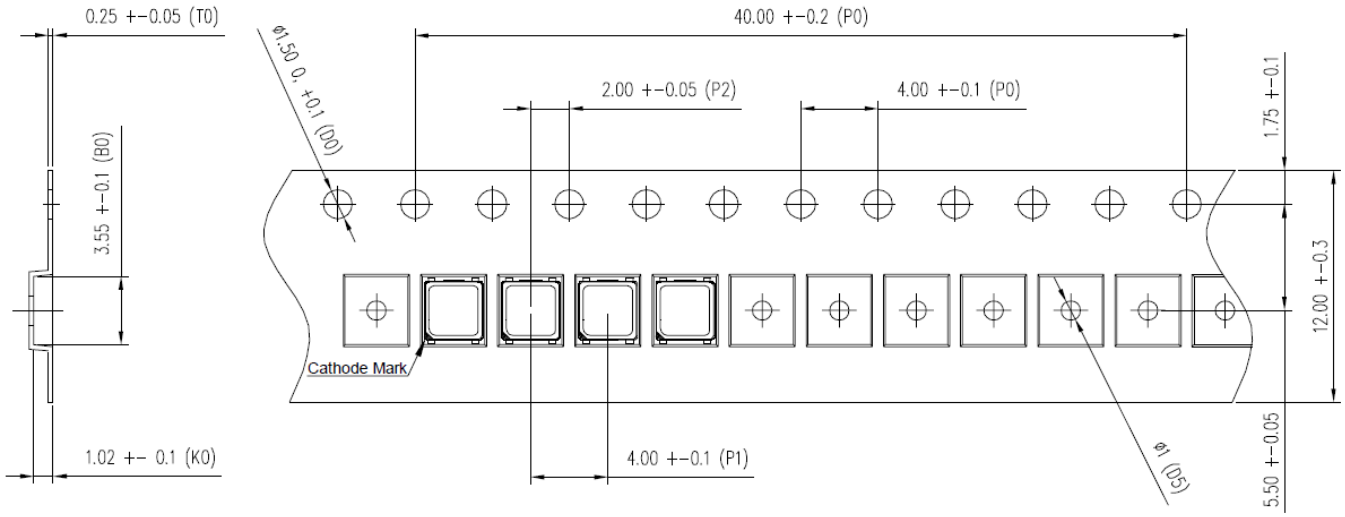
b) Manual Soldering Conditions

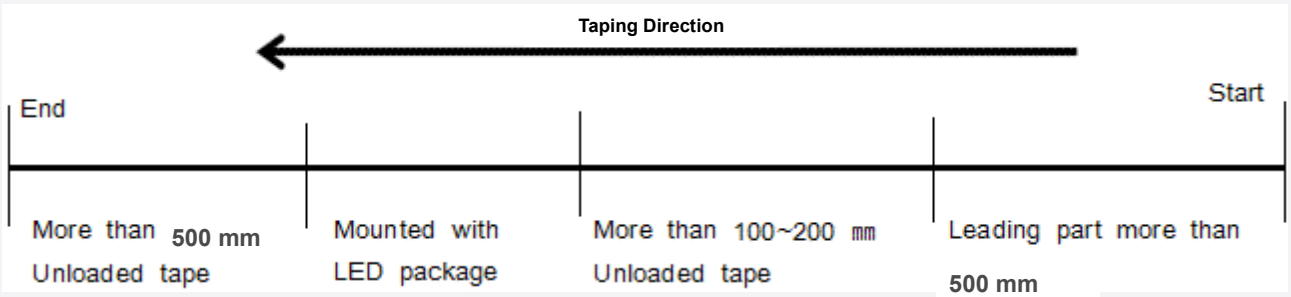
Not more than 5 seconds @ max. 300℃, under soldering iron.

7. Tape & Reel

a) Taping Dimension

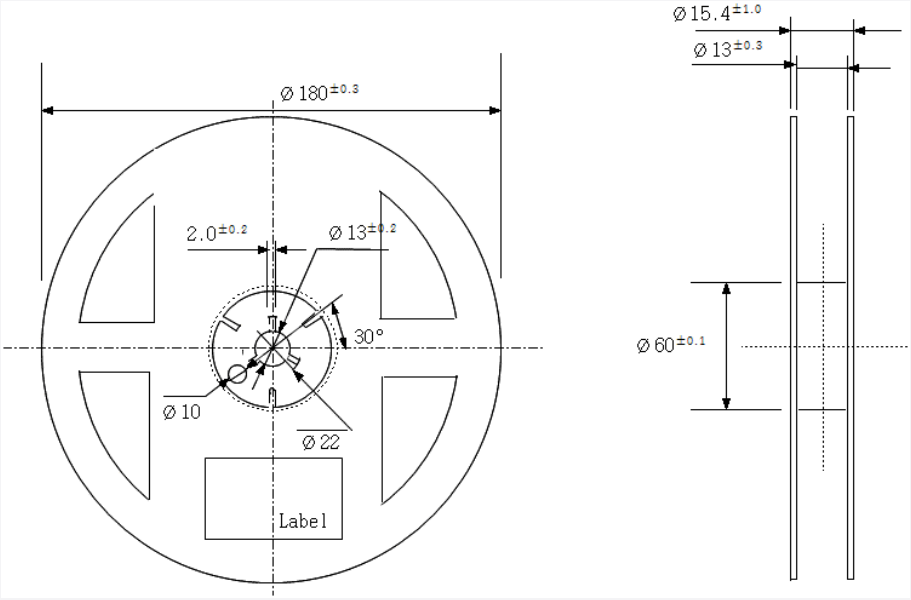
(unit: mm)





b) Reel Dimension

(unit: mm)

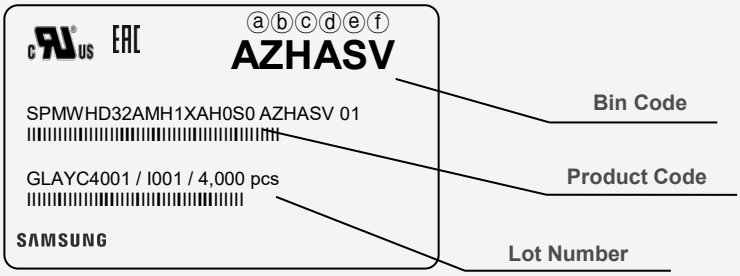


Notes:

1) Quantity: The quantity/reel is 4,000 pcs
2) Cumulative Tolerance: Cumulative tolerance / 10 pitches is ±0.2 mm
3) Adhesion Strength of Cover Tape: Adhesion strength is 0.1-0.7 N when the cover tape is turned off from the carrier tape at 10° angle to the carrier tape
4) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

8. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 5)

Bin Code:

ⓐⓑ: Forward Voltage bin (refer to page 8)

ⓒⓓ: Chromaticity bin (refer to page 10-13)

ⓔⓕ: Luminous Flux bin (refer to page 8)

b) Lot Number

The lot number is composed of the following characters:



①②③③②③④⑤⑥⑦⑧⑨ / Ⅰⓐⓑⓒ / 4,000 pcs

①② : Production site (GL: Tianjin, China, G4: Guangzhou, China)

※ Sample product (SL: Kiheung, Korea)

③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

④ : Year (Z: 2015, A: 2016, B: 2017…)

⑤ : Month (1~9, A, B, C)

⑥ : Day (1~9, A, B~V)

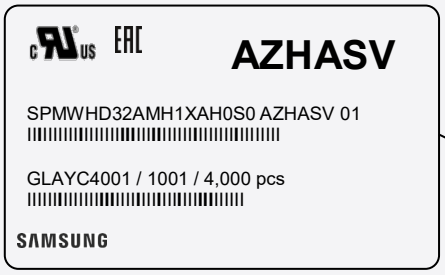
⑦⑧⑨ : Serial number (001 ~ 999)

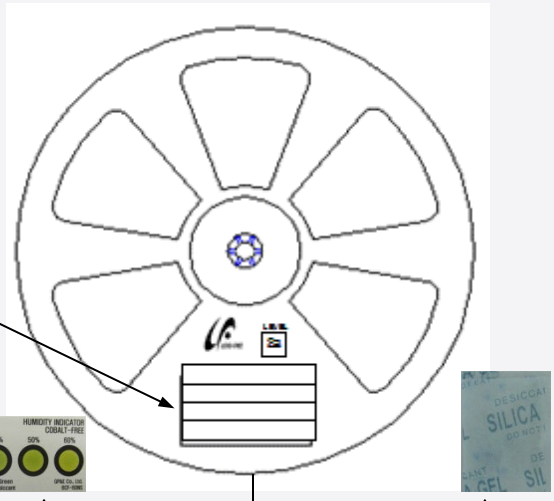
ⓐⓑⓒ : Reel number (001 ~ 999)

9. Packing Structure

a) Packing Process (The quantity of PKG on the Reel to be Max 4,000pcs)

Reel





Aluminum Vinyl Packing Bag



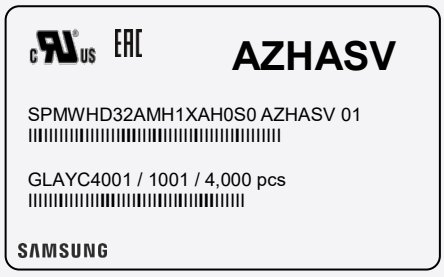


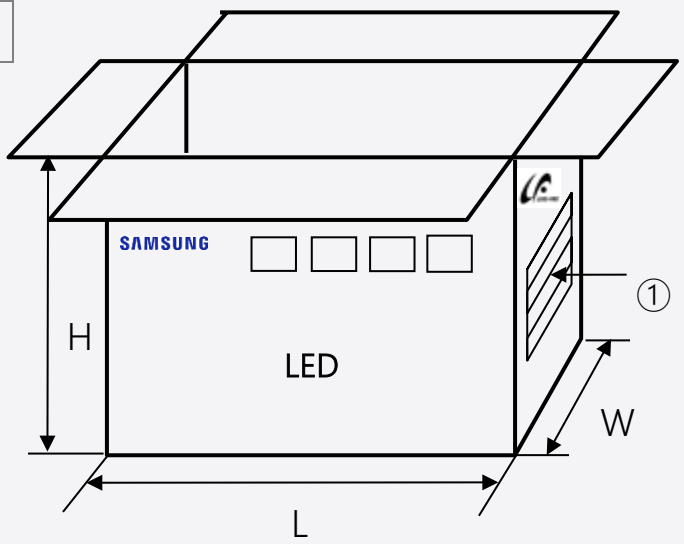
Outer Box

Material: Paper (SW3B(B))

Type	Size (mm)			Note
	L	W	H	
7 inch L	245 ± 5	220 ± 5	182 ± 5	Up to 10 reels
7 inch S	245 ± 5	220 ± 5	86 ± 5	Up to 5 reels

① **Side Label**





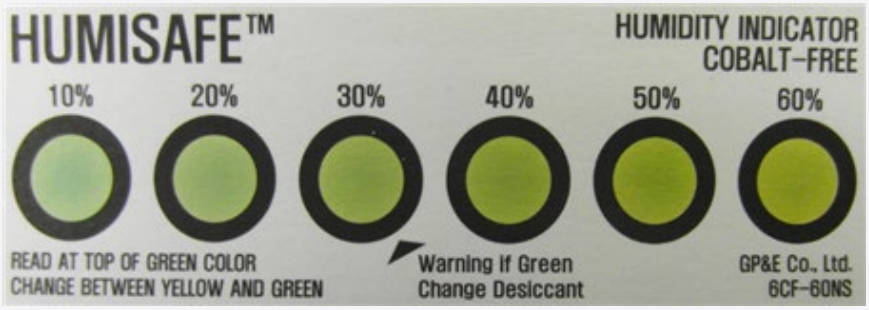
b) Aluminum Vinyl Packing Bag



c) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Bag

(This image is for reference only. Silica gel and humidity indicator shapes may be different.)





10. Precautions in Handling & Use

1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.

2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.

3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.

4) LEDs must be stored in a clean environment. Shelf life of sealed bags is 12 months at temperature 0~40 ºC, 0~90 % RH.

5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 ºC / 60 % RH*Note 1, or
b. Mounted within 24 hours (1 day) at an assembly line with a condition of more than 30 ºC / 70 % RH*Note 2, or
c. Stored at <10 % RH.

*Note 1, 2: IPC/JEDEC J-STD-033A, Recommended Equivalent Total Floor Life Table

Package Type and Body Thickness	Moisture Sensitivity Level	Maximum Percent Relative Humidity						Temperature
		40%	50%	60%	70%	80%	90%	
Body Thickness <2.1mm	Level 2a	∞	∞	28	1	1	1	30℃
		∞	∞	∞	2	1	1	25℃
		∞	∞	∞	2	2	1	20℃

6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.

7) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 ºC.

8) Devices must be baked for 10~24 hours at 60 ± 5 ºC, if baking is required.

9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.

10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.

11) Risk of sulfurization (or tarnishing)
The LED from Samsung uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as rubber, plain paper, lead solder cream, etc.

Legal and additional information.

About Samsung Electronics Co., Ltd.

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"Samsung provides limited warranty for its LED products, the full text of which is available at https://www.samsung.com/led/support/warranties"

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